



BEK Systemtechnik

Company Profile

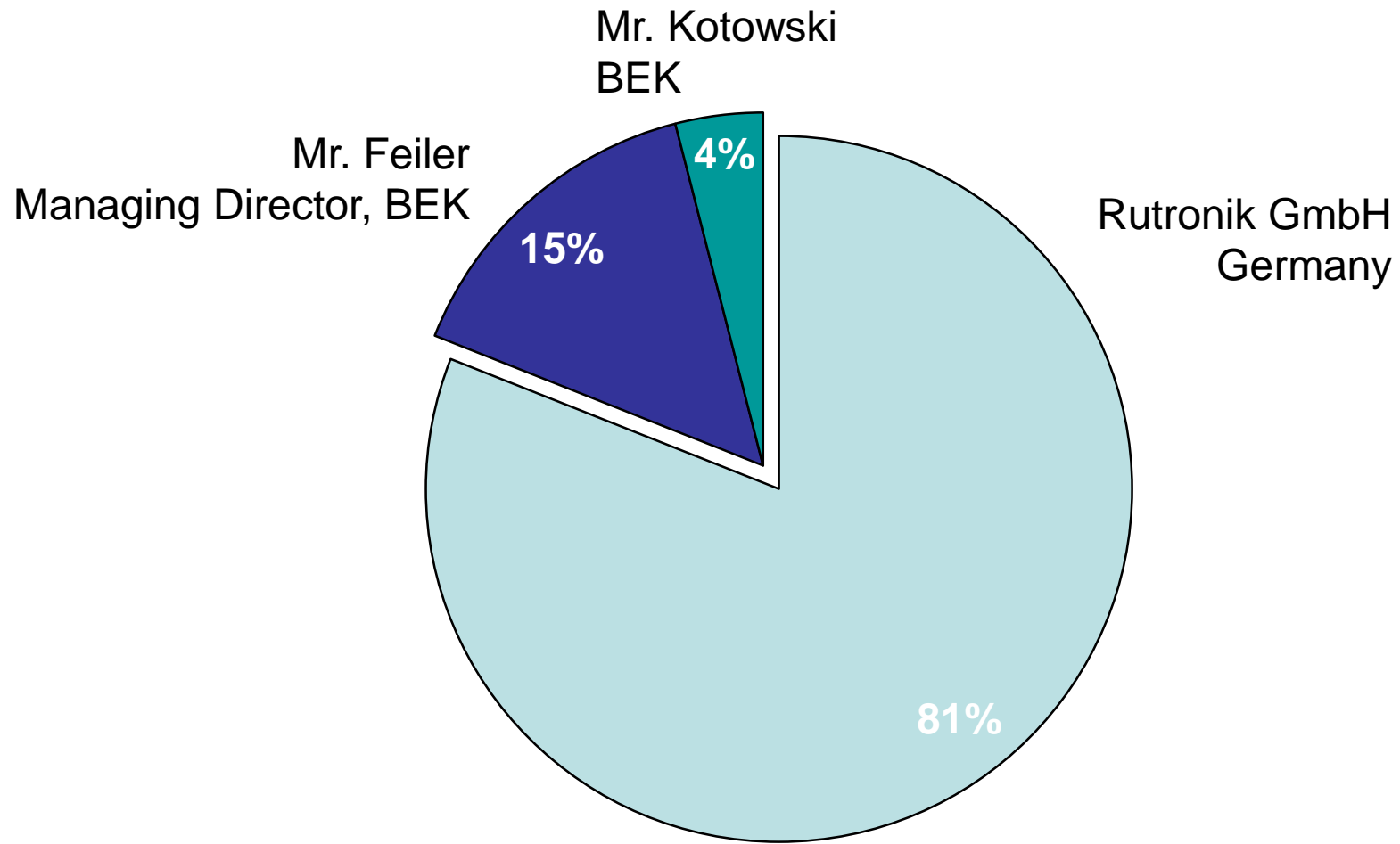
November 2020

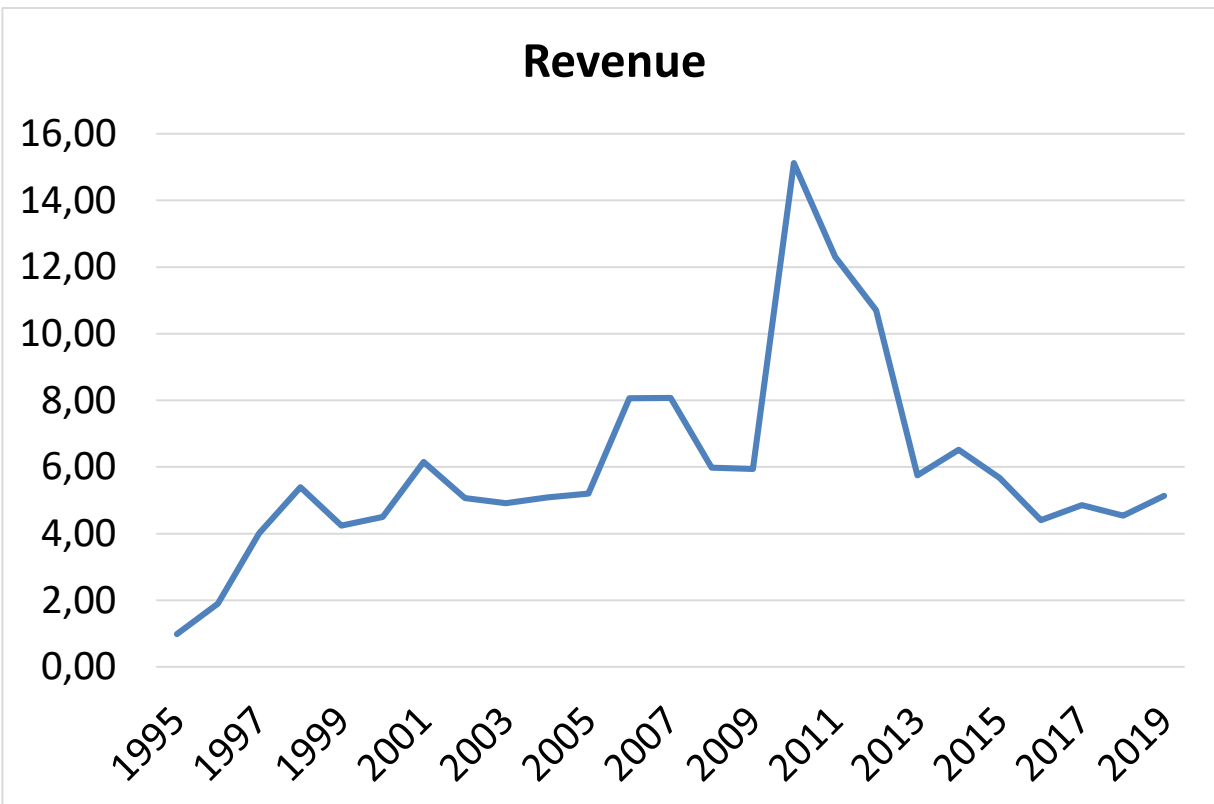
- 1983 Starting with Electronic Manufacturing at VEB Elektroprojekt Berlin
- 1995 **Foundation** of BEK Systemtechnik
- 1997 Duplication Manufacturing Area
- bis 2003 New N₂ soldering unit for wave soldering process
New Reflow-Soldering Machine and SMD- Assembly Units
- 2005/06 New Business-Unit for Inter Circuits Programming Service for
Microcontrollers, Memories, etc.
- 2007 Set-Up Incircuit- and Functiontest-System, Reinhardt ATS-KMFT-670M-2
- 2008 Upgrade SMD- Reflow-System 2009
- 2010 New acquisition of a N₂ wave soldering machine fully encapsulated
- 2018/19 Installation of second climate chamber, Feutron TPK200
- 2020 Extension of our service with THT component preparation
- today Shareholders' resolution for the strategic reorientation of BEK
Systemtechnik (new building and investment in machinery)

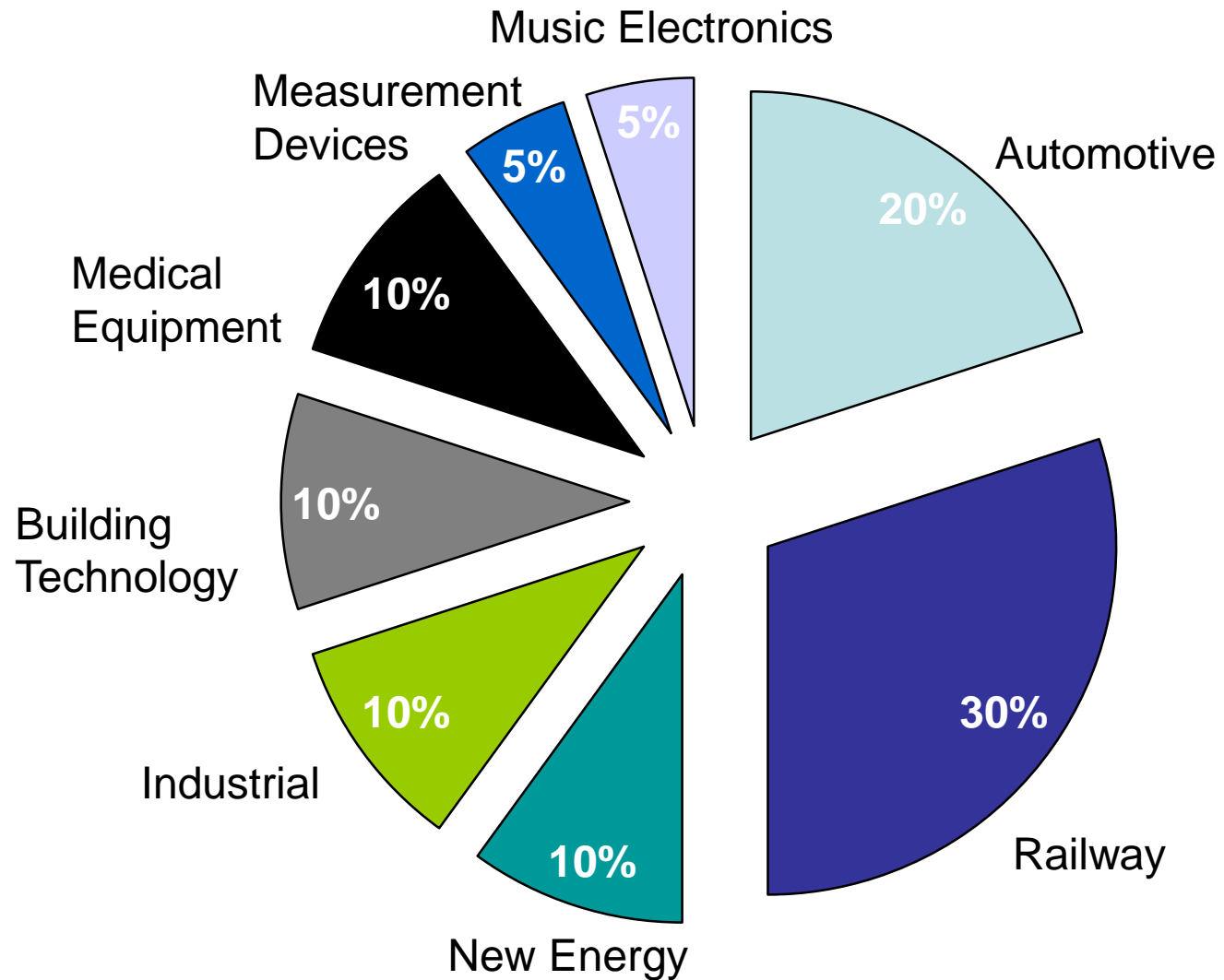


BEK Systemtechnik

Shareholders









BEK Systemtechnik

Our Competences

- Manual and automatic assembly of electronic components
- Complete production of assemblies in through-hole, mixed and SMD technology with machine soldering in a reflow continuous furnace or on a double wave soldering machine
- Press-in of contact pins and connector strips
- Painting of electronic assemblies
- Assembly of complete devices
- Optical inspection and electrical testing of components and complete devices
- Burn-in tests, temperature change tests in our climate chambers
- Procurement of components and provision of printed circuit boards on customer request
- Layout creation according to your circuit diagram
- Sample assembly, individual production, series production
- Inter Circuit Programming Service
- Stable and reliable supply chain, logistics
- Environmental Protection and Packaging Recycling



General

- maximum circuit board dimensions: 450 x 400 mm (larger dimensions are possible by agreement)
- fully automatic equipping
- short processing times in production and testing
- all workstations are ESD-protected
- universally applicable means of transport for the production flow
- customized packaging

Component Preparation

- Preparation of all commercial components for manual assembly with devices and tools
- automatic devices for beading, cutting and bending axial and radial taped components
- mechanical devices for preparing bulk material or special types of components

Manual Assembly

- Universal assembly workstations and repair workstations for sample assemblies and small series
- Placement and assembly workstations on the conveyor belt (linked with double wave soldering machine) for series production

Programmable circuit types:

- microcontrollers, memory, logic devices, crystals

Testing:

- Continuity Check
- Check Sum
- Blank Check, Device Check
- Misinsertion
- Compare Check
- Function Test
- Backward Device

Advantages at a glance:

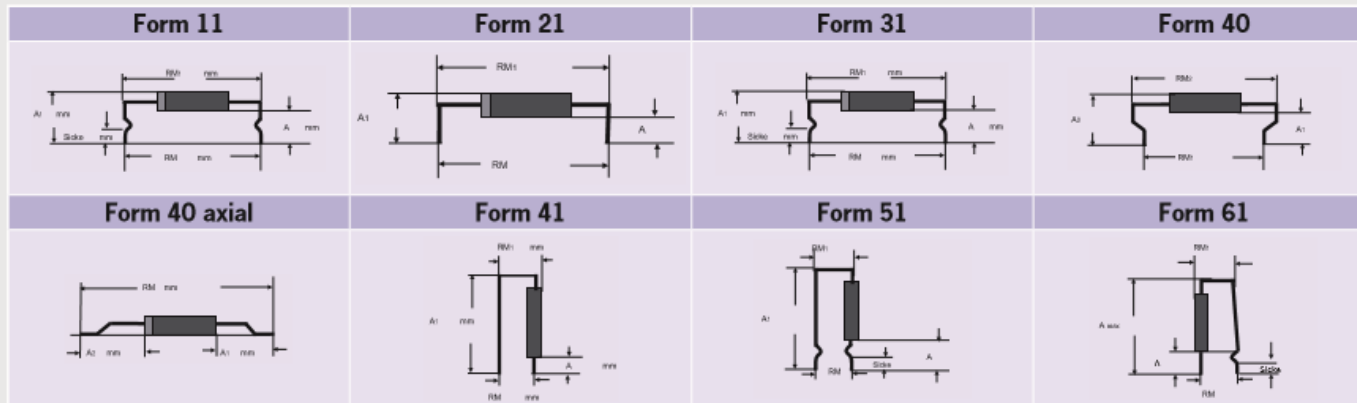
- Cost-effective
- Fully automatic
- Laser marking
- Much faster than by hand
- Minimized handling errors
- Components, logistics and support - all from one source



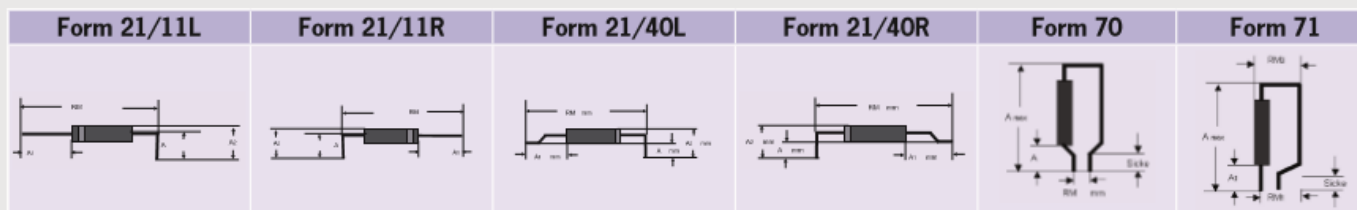
Cutting, bending, beading THT component preparation automated, tolerance safe & individual

The BEK cuts, bends and beads both axial and radial components. You decide how you provide the components: on belts in an ammopack, on rolls or, for smaller quantities, as bulk material. Fast processing times are guaranteed, not only for semi or fully automatic further processing. The BEK also cuts, bends and beads components with unusual specifications in the shortest possible time.

Axiale Biegeformen



Axiale Sonder-Biegeformen



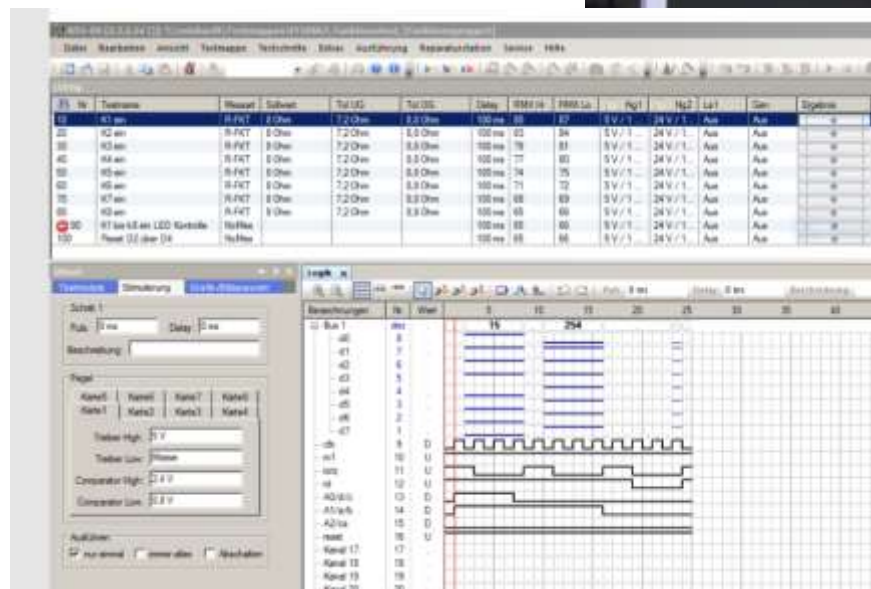
- Placement in adhesive or solder paste, interlinking with full convection oven
- Screen printing placement in solder paste, interlinking with full convection oven
- spectrum of components:
 - rectangular chips 0201 to 2225
 - melf, minimelf
 - SOT 23, SOT 89
 - QFP up to 0.4 pitch
 - BGA, μ BGA
 - Special designs
- smallest mountable package 01005 QFP, QFN, BGA, μ BGA from 0,4mm pitch
- automatic bad PCB detection
- optical correction system
- Boardloader and in-line transport chaining
- Maximum circuit board size for SMD assembly 905 * 590 mm



- Wave soldering machine for SMD and through-hole technology (lead-free and leaded)
- Options:
 - Inclined transport
 - Spray fluxer Density measuring
 - correction system
- Full convection reflow soldering machine
- 100% N2 use for machine soldering



- Visual inspection with automatic optical inspection (Orbotech) + Quins Easy
- Manual inspection with Vision "Mantis" PCB inspection device
- In-Circuit-Test with Reinhardt Multifunctiontest-system ATS-KMFT-670M-2
- Function Testing with Reinhardt Multifunctiontest-system ATS-KMFT-670M-2



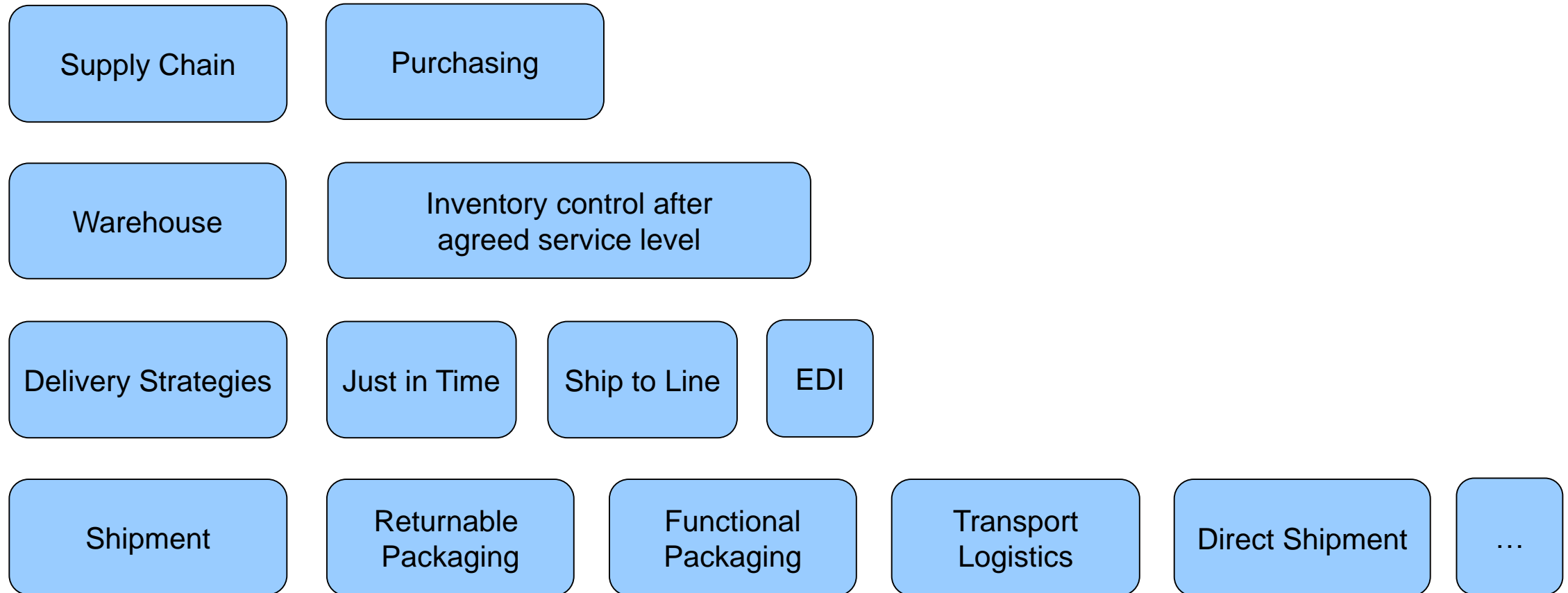
- Burn-in tests
- Thermal shock tests
- Active and passive



Our scope of services includes:

- employees trained according to IPC-A-610 standard
- Checking the printed circuit board data (layout problems etc.)
- Check according to design rules, check component arrangements
- component-related evaluation of pad sizes
- Checking the polarity or orientation of components
- Assembly illustration and visualization of problems before production start
- reliable preparation of all production data (SMD, AOI, selective)
- Consideration of test specifications and repair conditions
- Participation in the concept for electrical and functional testing













- Reliable partner for EMS services of our customers
- Competent advice
- Stable supply chain
- Unconditional quality
- High delivery reliability and ability to meet delivery dates
- Flexible and competent service
- Aftersales support




BEK Systemtechnik

Your Contact

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